



Printed Circuit Boards  
Interconnection Carriers

**PRINTED CIRCUIT BOARDS**

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31.10.2013

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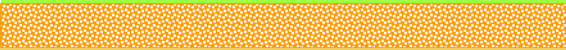

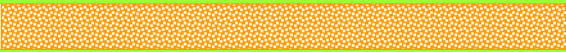


**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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04 121 FR4 35 L71.35 P18

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

04\_121\_FR4\_35\_L71.35\_p18

Layers	in $\mu$	Material	Build-Up	Assembly
Layer-1	35 $\mu$	Copper		 A1   B
	180 $\mu$	Prepreg		
Layer-2	35 $\mu$	Copper		
	710 $\mu$	L-FR4		
Layer-3	35 $\mu$	Copper		
	180 $\mu$	Prepreg		
Layer-99	35 $\mu$	Copper		

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